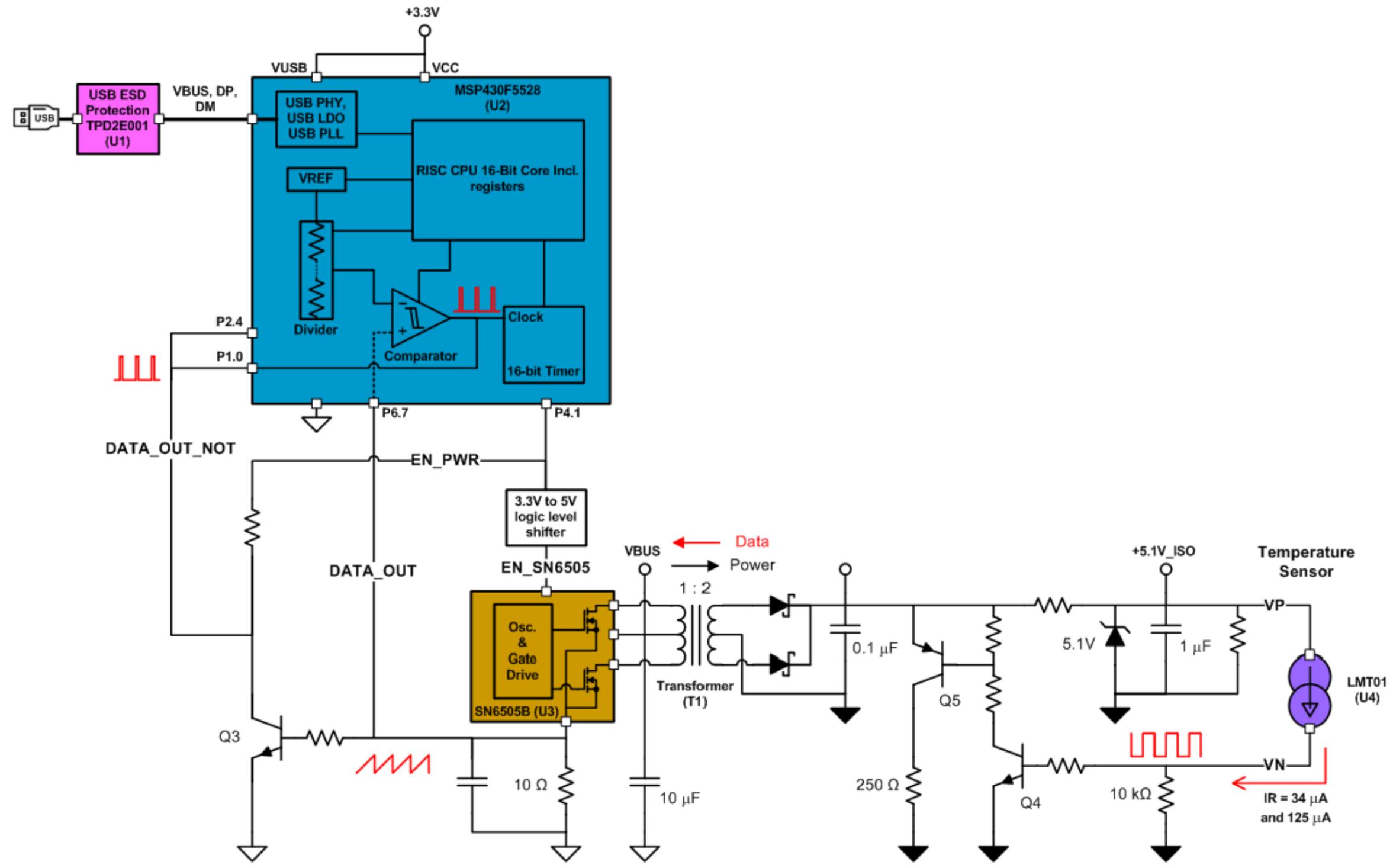


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

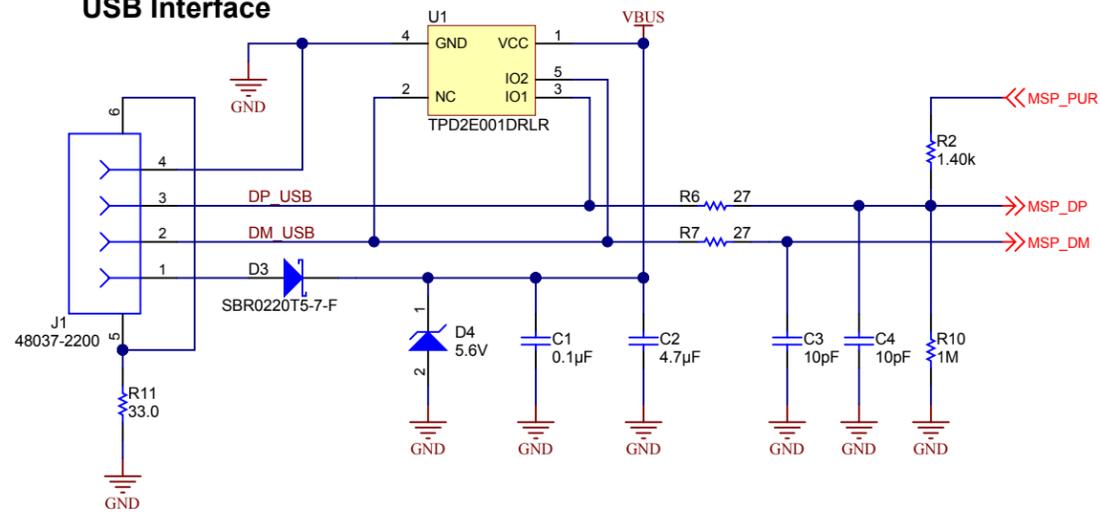


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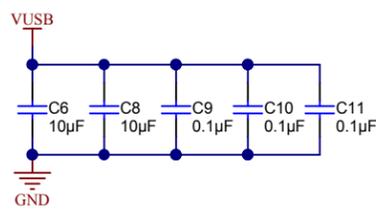
Orderable: N/A	Designed for: Public Release	Mod. Date: 12/9/2015
TID #: TIDA-00752	Project Title: 2-Wire Galvanically Isolated IC Temperature Sensor	
Number: TIDA-00752	Rev: E1	Sheet Title: System Block Diagram
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3
Drawn By: SY	File: TIDA-00752_E1_CoverSheet_SchDoc	Size: B
Engineer: SY	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



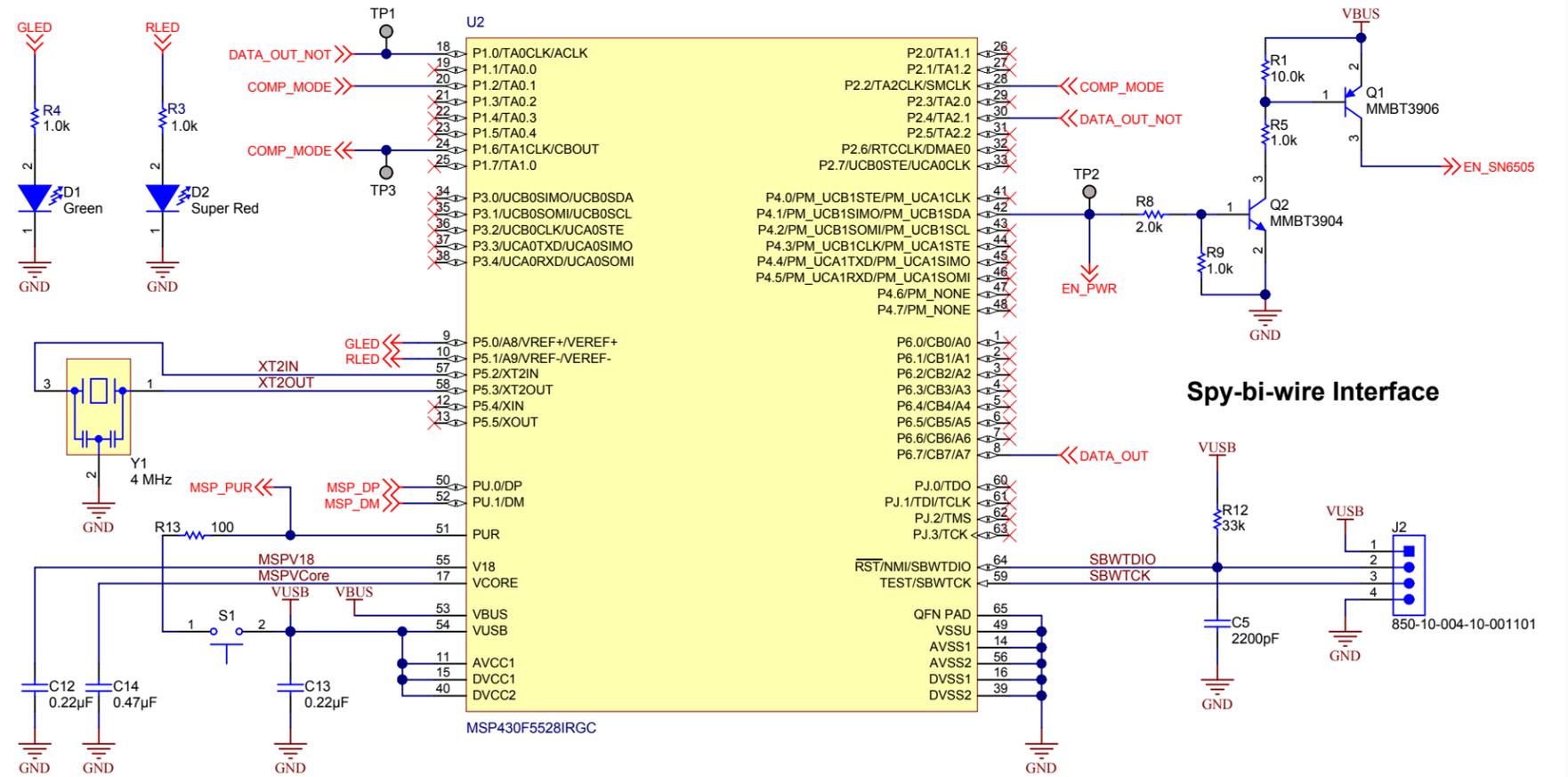
### USB Interface



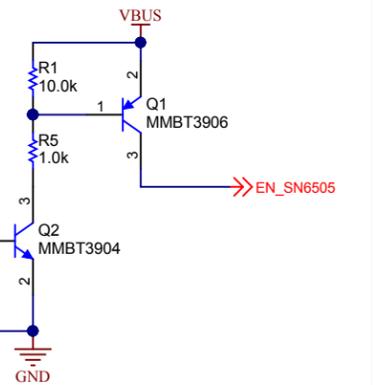
### De-coupling Capacitors



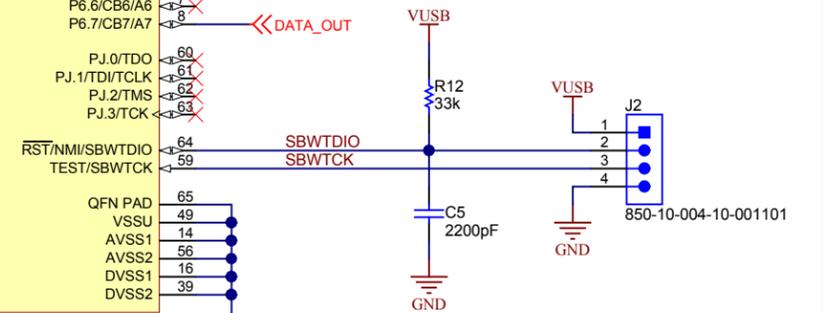
### MSP430F5528 MCU



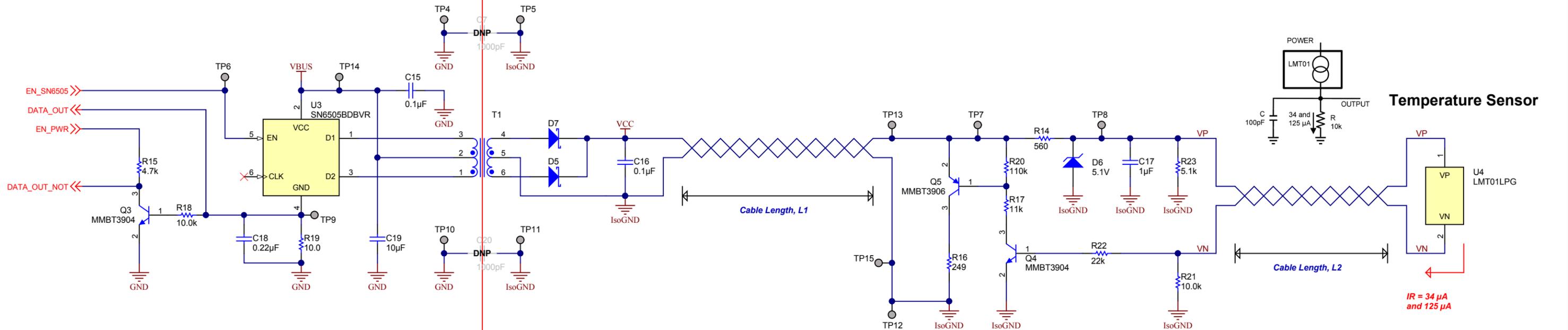
### 3.3V to 5V Level Shifter



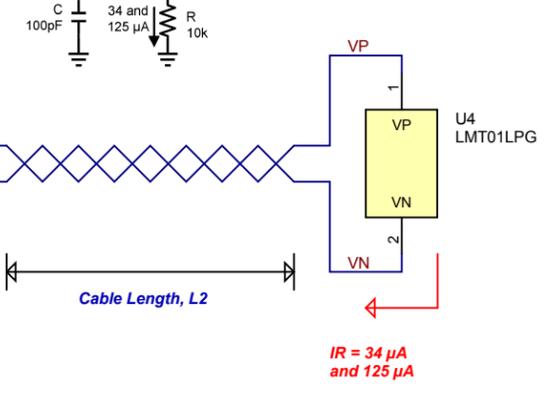
### Spy-bi-wire Interface



### Isolated DC-DC Converter (Push-Pull Topology)



### Temperature Sensor



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TID #: TIDA-00752	Project Title: 2-Wire Galvanically Isolated IC Temperature Sensor	
Number: TIDA-00752	Rev: E1	Sheet Title: MSP430 MCU & LMT01 Interface Circuitry
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By: SY	File: TIDA-00752_E1_MSP430_LMT01.SchDoc	Size: B
Engineer: SY	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	© Texas Instruments 2015



PCB Number: TIDA-00752  
PCB Rev: E1

PCB  
LOGO  
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PCB  
LOGO  
Pb-Free Symbol

PCB  
LOGO  
ESD Susceptible

PCB  
LOGO  
Texas Instruments

PCB  
LOGO  
Texas Instruments

PCB  
LOGO  
ESD Susceptible

Label Table	
Variant	Label Text
001	TIDA-00752 E1

ZZ1  
**Assembly Note**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2  
**Assembly Note**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3  
**Assembly Note**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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TID #: TIDA-00752	Project Title: 2-Wire Galvanically Isolated IC Temperature Sensor		
Number: TIDA-00752	Rev: E1	Sheet Title: Hardware Items	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3	
Drawn By: SY	File: TIDA-00752_E1_TID_Hardware.SchDoc	Size: B	
Engineer: SY	Contact: http://www.ti.com/support		

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